

Notice of References Cited	Application/Control No. 101 630, 776	Applicant(s)/Patent Under Reexamination GOTO ET AL.	
	Examiner Saif A. Alhija	Art Unit 2128	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
*	A	US-5,327,358	07-1994	Stubbs, Norris	702/36
	B	US-			
	C	US-			
	D	US-			
	E	US-			
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
*	U	Liu "System Implementation, Modeling, and Defects Pattern Recognition for Flip Chip Solder Joint Inspection using Laser Techniques" March 2001.
*	V	MSC.Nastran 2001 Installation and Operations Guide
*	W	ANSYS Software Package, 2001
	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.